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TITLE: 483 I/O FC CBGA, 29 X 29 PKG, 1.27MM PITCH, WITH CAP ZONES	DOCUMENT NO: 98ARE10653D	REV: B
	STANDARD: NON-JEDEC	
	SOT1608-1	04 JAN 2016



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.

6. CAUTION MUST BE TAKEN NOT TO SHORT EXPOSED METAL CAPACITOR PADS ON PACKAGE TOP.

7. ALL DIMENSIONS ARE SYMMETRICAL ABOUT THE CENTER LINES UNLESS OTHERWISE SPECIFIED.

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